

LASER PROCESSING APPARATUS

ABSTRACT

A laser processing apparatus includes a laser beam applying unit for applying a laser beam to a wafer to be processed. The laser beam applying unit includes a laser oscillator for emitting the laser beam, a beam condenser for focusing the laser beam emitted from the laser oscillator into a focused spot and positioning the focused spot in the wafer held on a chuck table, a focused spot position adjuster disposed between the laser oscillator and the beam condenser for adjusting the position of the focused spot, and an upper surface position detector for detecting the position of an upper surface of the wafer. The upper surface position detector includes a first upper surface position detecting unit, a second upper surface position detecting unit, and a selector for selecting either the first upper surface position detecting unit or the second upper surface position detecting unit depending on a feature of the wafer.

[FIG. 2]